

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJCD2003
Package Type :	DFNWB2x3-6L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	2.5037%
Lead Frame	Cu	7440-50-8	93.50%	46.4978%
	Fe	7439-89-6	2.30%	
	Silver	7440-22-4	4.00%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.12%	
Epoxy	Silver	7440-22-4	77.00%	2.3845%
	Epoxy resin	Proprietary	15.00%	
	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	6.00%	
	Aromatic polyamine	Proprietary	2.00%	
	Silver	7440-22-4	75.00%	
	Epoxy resin	Proprietary	22.00%	
	Curing agent & hardener	Proprietary	3.00%	
	Silver	7440-22-4	80.50%	
	Epoxy acrylate UV resin	55818-57-0	4.00%	
	Phenoxyisopropanol	770-35-4	7.00%	
	4-Methyl-2-phenyl-1H-imidazole	827-43-0	1.50%	
	Epoxyresin(Non-hazardous)	Proprietary	7.00%	
Wire1	Copper	7440-50-8	98.15%	0.3974%
	Palladium	7440-05-3	1.85%	
Wire2	Copper	7440-50-8	97.90%	0.2285%
	Palladium	7440-05-3	1.80%	
	Gold	7440-57-5	0.30%	
Mold Compound	Epoxy Resin A	Trade Secret	7.00%	43.3184%
	Phenol Resin	Trade Secret	3.00%	
	Silica(Amorphous) A	60676-86-0	82.50%	
	Silica(Amorphous) B	7631-86-9	7.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.99%	4.6696%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.